



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP295 H6327		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001084548						
<b>Package</b>		PG-SOT223-4-21		<b>Weight*</b>		113.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.078	0.07		684	
	non noble metal	tin	7440-31-5	0.020	0.02		176	
	inorganic material	silicon	7440-21-3	0.881	0.77	0.86	7747	8607
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1338	
	non noble metal	copper	7440-50-8	50.489	44.43	44.61	444188	446061
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	517	517
encapsulation	organic material	carbon black	1333-86-4	0.600	0.53		5274	
	plastics	epoxy resin	-	8.993	7.91		79113	
	inorganic material	silicondioxide	60676-86-0	50.358	44.30	52.74	443035	527422
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12880	12880
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4513	4513
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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